EECO-Green
SILVER THROUGH HOLE PCB
DESIGN RULES

Item	Feature Description	Preferred Dimension	Minimum Acceptable
A	Hole Pitch	1.50 mm	1.25 mm
B	Silver Through Hole Land	1.00 mm (Max)	0.80 mm
C	Copper Land Diameter	1.25 mm	1.00 mm
D	Space Between Copper Lands	0.25 mm	0.20 mm
E	Space between Copper Land and Trace	0.25 mm	0.20 mm
F	Copper Trace Width	0.25 mm	0.20 mm
G	Space between Copper Traces	0.25 mm	0.20 mm
H	Through Hole Overcoat Diameter		Copper Land + 0.30 mm
I	Space Between Copper Land and Board Edges		2.00 mm
J	Space Between Copper Land Scoring line (V-Cut)		1.00 mm
K	Space Between Silver Through Hole Land and Closest Edge of Punched Hole		1.60 mm
L	Space Between STH Copper Lands and SMD pads	> 0.50 mm	0.50 mm
M	Space Between STH Copper Lands and Carbon Pad	1.2 mm	1.00 mm
	Silver Through Hole Diameter (Typ.)		0.50 mm

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ELECTRICAL SPECIFICATIONS

#	Characteristic	Specification
1	Silver Through Hole Voltage	Maximum 50V DC
2	Silver Through Hole Resistance	Maximum 100mΩ / Silver Through Hole
3	Silver Through Hole Rated Current *	Maximum 1 Amp / Silver Through Hole
4	Silver Through Hole Insulation Resistance	Minimum 10^8 Ω

* Use multiple Silver Through-Holes in parallel for greater current-carrying capacity

MATERIALS SPECIFICATIONS [1]

#	Characteristic	Specification
1	Laminate	FR-1
2	Copper Thickness	1 OZ (35µ)
3	Board Thickness	1.0 mm ~ 1.6 mm
4	Panel Size	Maximum 350 X 330 mm

[1] Other laminates available – contact factory

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